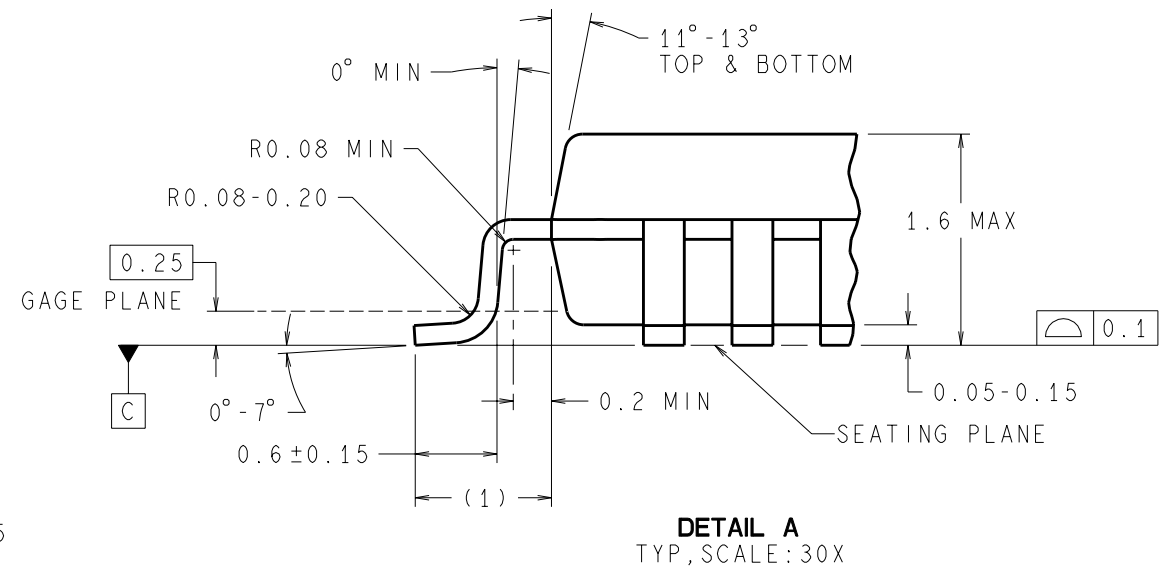
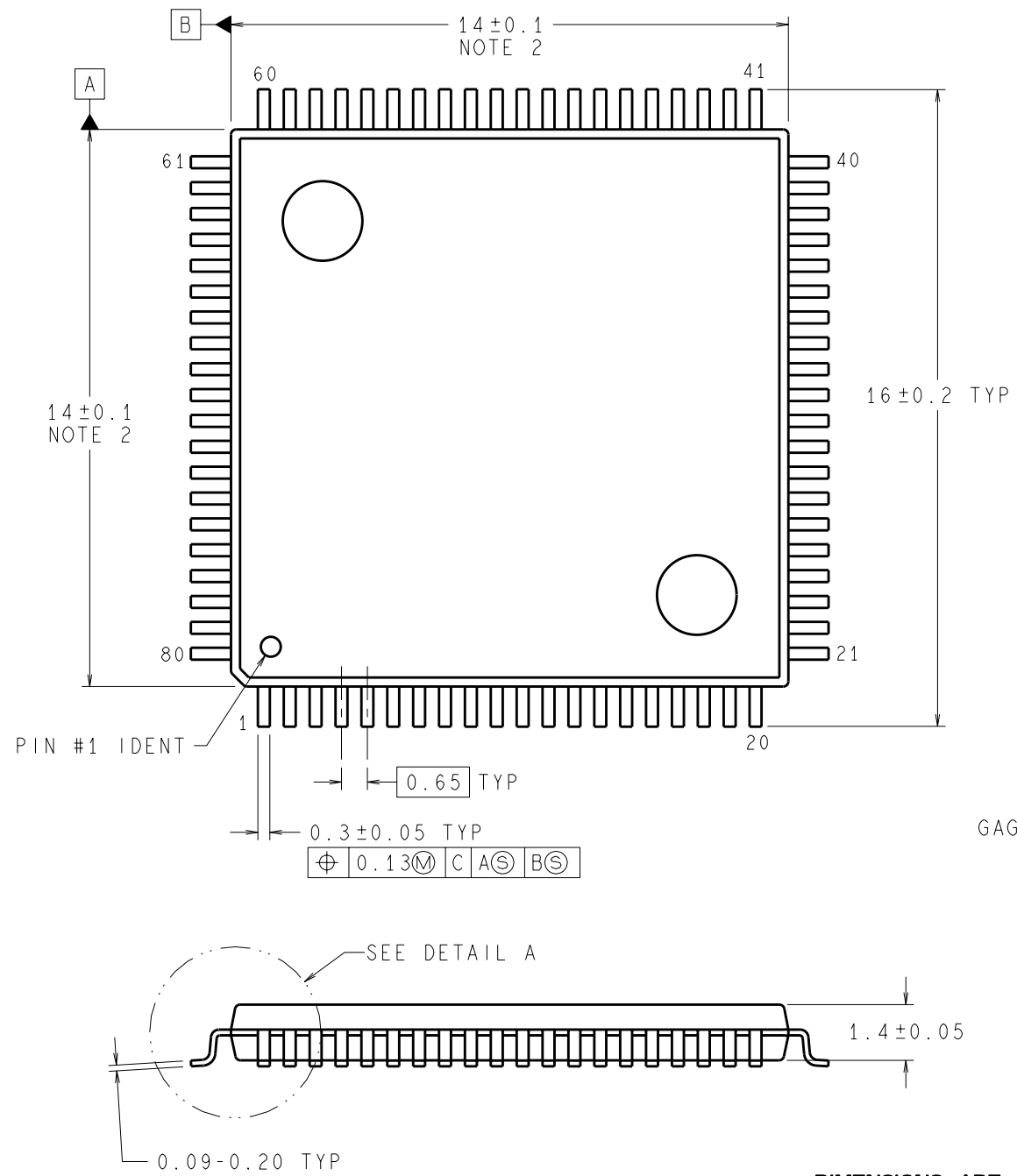


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
B	TITLE: LQFP WAS PQFP; UPDATE NOTE 3; ADD GEOMETRIC TOLERANCE; REDRAW	12317	12/03/1999	ACS/MS/RW



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. STANDARD LEAD FINISH:
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
THICKNESS ON COPPER.
2. DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
3. REFERENCE JEDEC REGISTRATION MS-026, VARIATION BEC,
DATED FEBRUARY 1999.

APPROVALS	DATE	National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090			
DRAWN MARTA SUCHY	12/03/1999				
DFTG. CHK. THANH LEQUANG	12/08/1999				
ENGR. CHK. RANDALL WALBERG	12/08/1999	LQFP, JEDEC METRIC, 14 X 14 X 1.4mm, 80 LEAD			
PROJECTION INCH [MM]					SCALE N/A
FORMERLY:		SHEET 1 of 1			